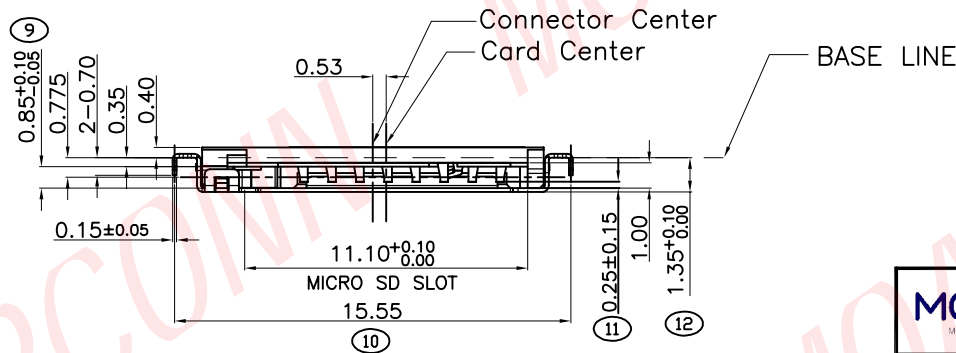
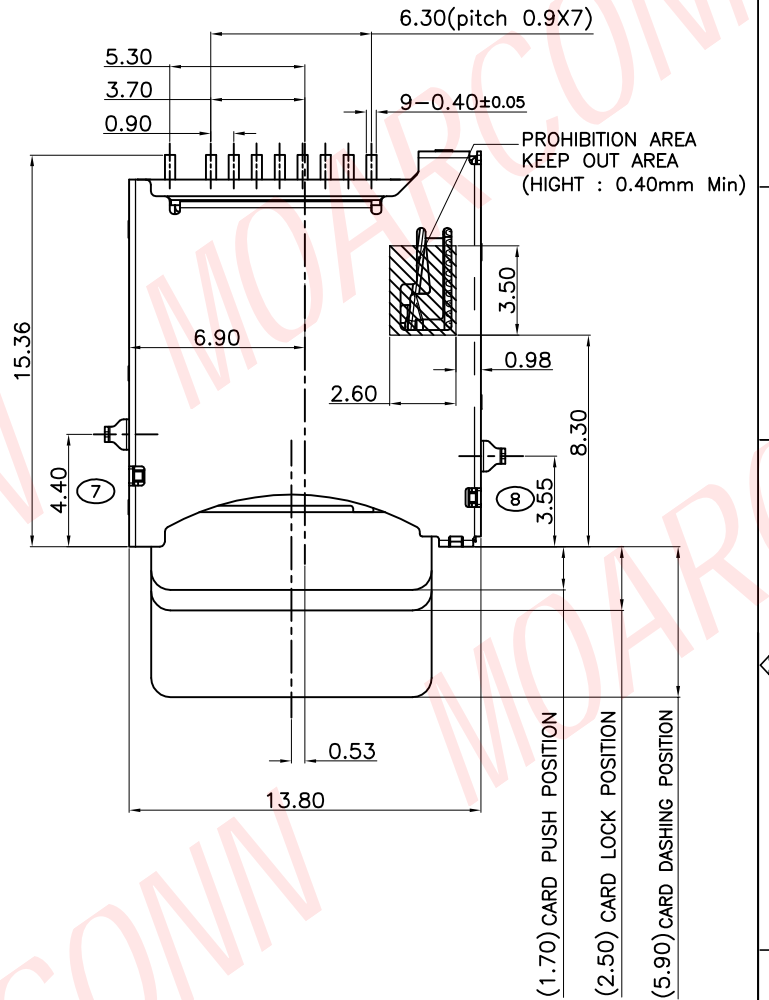
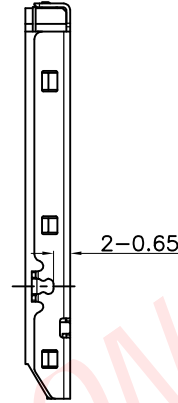
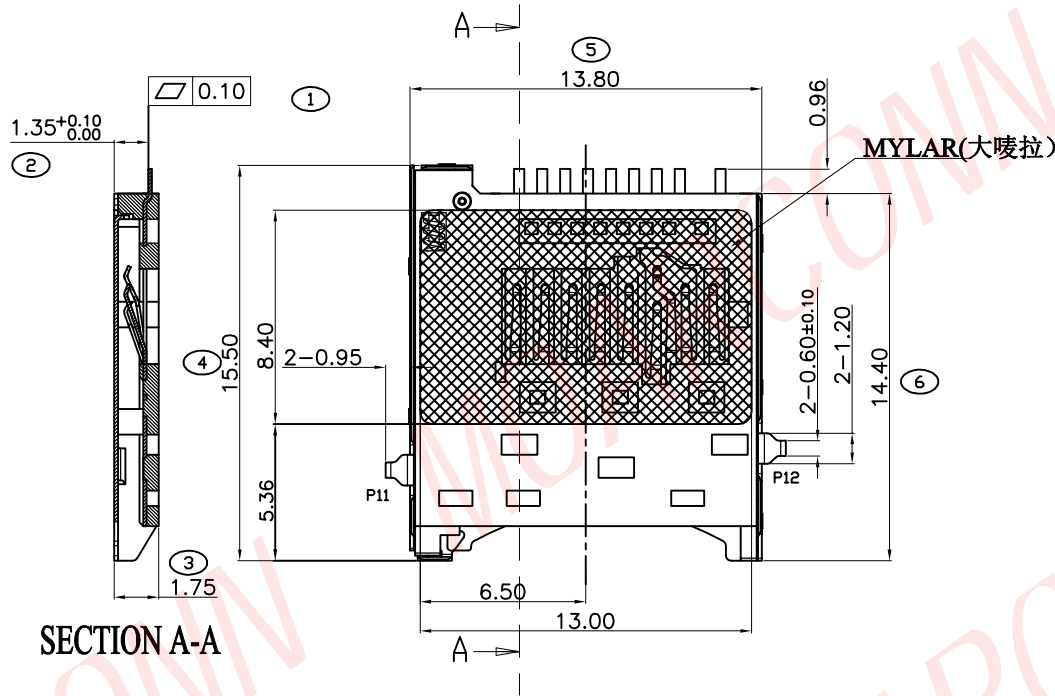


All materials, plating and process meet HF requirements.

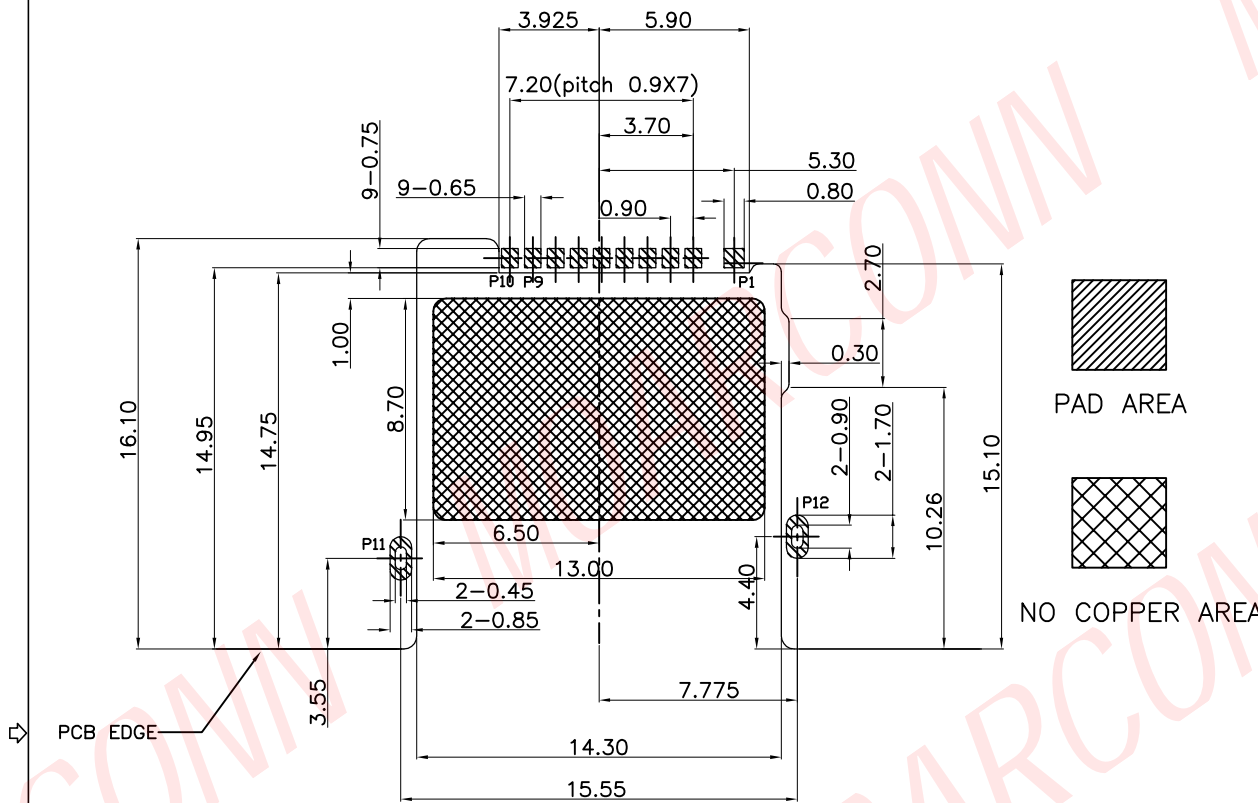


SECTION A-A

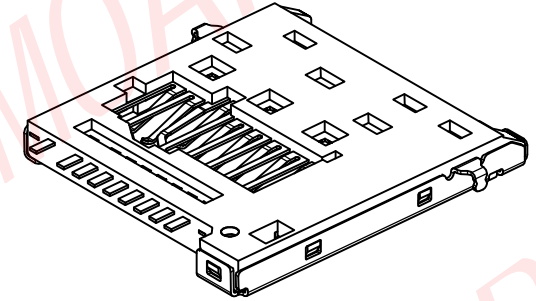
MOARCONN <small>MORE CONNECTIONS SMART FUTURE</small>		DONG GUAN MOARCONN ELECTRONIC Co., Ltd.			
		DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE	PRODUCT NAME : MICRO SD CARD CONN. BOTTOM MOUNT SINK 1.35mm	DRAWING: Alexander	DATE: 2021.02.22
DIMENSION TOLERANCE X.X: ± 0.35 X.XX: ± 0.25 X.XXX: ± 0.10 ANGULAR: ± 2'	PRODUCT NO. : MS135-T1230-51	CHECK:	DATE:		
	DRAWING NO. : D-MS135-T1230-51	APPROVED:	DATE:		
		SCALE: 1:1	DWG ID: C D	REV.: A	PAGE: 1 of 2

A	---	NEW RELEASE	Alexander	2021.02.22
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1				
2				
3				

All materials, plating and process meet HF requirements.



Pin Define	
P1	SWITCH TERM CD
P2	DAT1
P3	DAT0
P4	VSS
P5	CLK
P6	VDD
P7	CMD
P8	CD/DAT3
P9	DAT2
P10	GND
P11	GND
P12	GND



PCB PATTERN LAYOUT
(GENERAL TOLERANCE:±0.05)

Specification

***Electrical Characteristics:**

Contact Current Rating:0.5Amperes.
Dielectric Withstanding Voltage:AC500V r.m.s.
Insulation Resistance:1000 Megohms
Minimum At DC 500V.
Contact Resistance:100 mΩ Maximum.

***Mechanical Characteristics:**

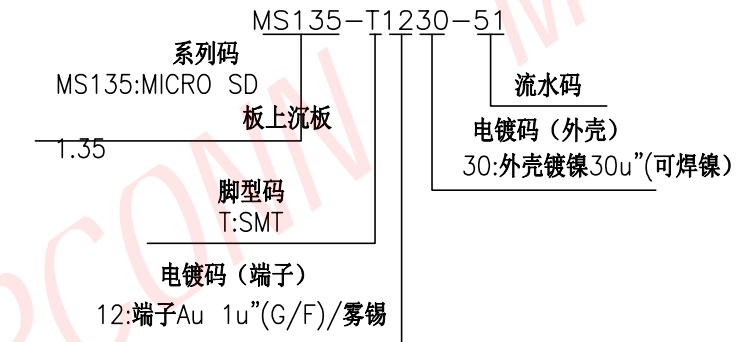
Mating Cycles:10,000 Cycles.

***Environmental:**

Operating Temperature:-25°C~+85°C.

***Materials:**

Insulator:HI-Temp plastic UL 94V-0 Rated.
Contact:Copper Alloy.
Shell:Stainless Steel(t=0.15mm).



		DONG GUAN MOARCONN ELECTRONIC Co., Ltd.			
		PRODUCT NAME : MICRO SD CARD CONN. BOTTOM MOUNT SINK 1.35mm	DRAWING: Alexander	DATE: 2021.02.22	
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		SCALE: 1:1	DWG ID: C D	REV.: A	PAGE: 2 of 2

A	-----	NEW RELEASE	Alexander	2021.02.22
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1				